

INTERFLUX[®] SOLDER NV MATERIAL SAFETY DATA SHEET



	Date of publication : 12/02/98 Revision date : 21/06/05
SAFETY DATA SHEET	Version : 7
International Standard	ISO 11014-1
	Xn : Harmful

1. PRODUCT AND COMPANY IDENTIFICATION

Product name :	IF 14 Low Residue Solderwire
	IF 14-09 Very Low Residue Solderwire
	IF 14-06 Very Low Residue Solderwire
Main supplier :	Interflux [®] Solder NV
	Eddastraat 51
	BE - 9042 Gent
	Tel. Nr. : ++32-9-251.49.59
	Fax nr. : ++32-9-251.49.70
Collect call for emerg	gency : ++1-703-527-3887 (Chemtrec)

2. COMPOSITION AND INFORMATION ON INGREDIENTS

The solderwire IF 14 is a preparation. Chemical nature Components contributing to the hazard :

	<u>Materials</u>	<u>CAS N°</u>	<u>% Range</u>	Alloy
*	Tin	7440-31-5	59.5% - 60.5%	Sn60Pb40
	Lead	7439-92-1	remainder	
	Flux incorporated	-	$1.4\% (\pm 0.2\%)$	
*	Tin	7440-31-5	62.5% - 63.5%	Sn63Pb37
	Lead	7439-92-1	remainder	
	Flux incorporated	-	0.6% - $0.9%$ (± $0.3%$)	
	-		1.4% (±0.2%)	
*	Tin	7440-31-5	61.5% - 62.5%	Sn62Pb36Ag2
	Lead	7439-92-1	remainder	
	Silver	7440-22-4	1.8% - 2.2%	
	Flux incorporated	-	0.6% - 0.9% (±0.3%)	
	_		1.4% (±0.2%)	
*	Tin	7440-31-5	4.8% - 5.2%	Sn5Pb93Ag2
	Lead	7439-92-1	remainder	
	Silver	7440-22-4	1.2% - 1.8%	
	Flux incorporated	-	0.6% - 0.9% (±0.3%)	
	_		1.4% (±0.2%)	

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All other information is strict confidential and will only be given on request of a doctor or a medical department who is obligated to a total confidentiality.

3. HAZARDS IDENTIFICATION

Hazard designation : Xn harmful.

Specific hazards for humans and environment : None. Physical and chemical hazard :			
- Incompatibility	:	None.	
Decomposition		Tin lead and silver compound	

- Decomposition : Tin, lead and silver compounds.
- Polymerisation : Will not occur.

4. FIRST-AID MEASURES

Inhalation	: None, if the area is well ventilated. Without ventilation it can cause very little irritation to the throat and the eyes.
Skin contact	: Burns ; cool affected parts under running water. Do not remove adhering material, apply a sterile dressing and seek medical advice.
Eye contact Ingestion	Irrigate immediately with copious amounts of water for several minutes.Obtain medical attention.

5. FIRE-FIGHTING MEASURES

Suitable extinguishing media	:	CO ₂ , sand or dry earth, dry chemical powder. Do not use jet of water.
Protection of fire-fighters	:	A SCBA mask is recommended when entering the fire area.
Fire & explosion hazards	:	None.
Special protective equipment	for	a fire : Wear a respiratory mask.
Flash point of flux	:	170°C

6. ACCIDENTAL RELEASE MEASURES

Personal precautions	:	None.	
Environmental precaution	ns:	Do not allow spill to spread to sewer or ground.	
Methods for cleaning up	:	Prevent entry into drains, sewers and water sources. Residues should be	
		stored in closed containers. Disposal should be done in accordance with Local. State or National Legislation.	
		ocal, State or National Legislation.	

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7. HANDLING AND STORAGE

Handling Technical measures	:	Avoid breathing fumes. Use only in well ventilated areas. Wash hands thoroughly after handling this product. No eating, drinking or smoking is allowed in the working area. Wear gloves.		
Precautions for safe handling	:	General ventilation should be provided.		
Storage Technical measures	:	No special precautions. IF 14 has a shelf life of minimum 2 years.		
Storage conditions Incompatibility of the product Safe packaging materials	: :	Storage class : 10-13.VbF-class : None.Please refer to the above section "Technical Measures".Not applicable.Not applicable.		

8. EXPOSURE CONTROLS / PERSONAL PROTECTION

Engineering measures : H	Refer to section 7.	
Control parameters : 7	Freshold limit values	(MAC)
Substance		8 hr TWA
Fumes from flux in the wire		0.1 mg/m^3
Silver fumes		0.01 mg/m^3
Tin compounds, inorganic (as S	Sn)	2 mg/m^3
Lead, inorganic dust and fumes	(as Pb)	0.15 mg/m^3
Personal protective equipment	ıt	
Special instructions for protection	ction and hygiene :	Industrial hygiene is always recommended. Wash
	t	he hands with water and soap after working.
Respiratory protection	: Nor	e required if adequate ventilation is present.
Hand protection	: Prot	ective gloves.
Eye protection	: Use	safety glasses/goggles.

: Additional protection equipment is normally not required.

9. PHYSICAL AND CHEMICAL PROPERTIES

Physical state Colour Odour	:	Solid Silver metal No smell		
pH, 5% aq. so	lution		:	3
Flash Point of	flux		:	170°C
Melting point	Sn63	Pb37	:	183°C
	Sn60	Pb40	:	183-190°C

Skin and body protection

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URL: http://www.interflux-electronics.com



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Sn62Pb36Ag2	:	178-190°C
Sn5Pb93Ag2	:	296-301°C
Density of flux	:	\pm 1.2 g/ml
Solubility in water	:	Insoluble

10. STABILITY AND REACTIVITY

Stability Hazardous reactions Conditions to avoid Materials to avoid Hazardous decomposition products	: : :	Stable Not applicable. High temperatures. None known. Tin lead and silver compounds
Hazardous decomposition products	:	Tin, lead and silver compounds.

11. TOXICOLOGICAL INFORMATION

Acute toxicity : Interflux[®] solderwire IF 14 contains a non-corrosive and non-toxic flux. It can cause slight irritation on the skin.

Other information on health effects : Normal handling of this product causes no skin irritation but the use of gloves and a good industrial hygiene is always recommended.

Proprietary ingredient(s)

	(~)
<u>Risk effects on hu</u>	<u>mans</u>
Inhalation :	Hazardous decomposition products are generated at high temperatures.
Skin contact :	Heated material may cause burns.
Eye contact :	Vapour can cause little irritation.
Risk effect on anim	mals
Rabbits :	Must be considered as an irritant.
Skin contact :	The skin becomes sensible after overexposure.

12. ECOLOGICAL INFORMATION

Environmental information : Tin, lead and silver compounds are not biodegradable and may therefore not be disposed in the environment.

General information :

- WGK : Tin (class 0), lead (class 2) and silver (class 3). Do not dispose into the groundwater, the drainage or the sewerage. Already pollution of the drinking-water when very small quantities of the product are disposed into the subsoil.
- Prevent the emission of this product to the environment by blocking the drains, access to water and access to fields.

13. DISPOSAL CONSIDERATIONS

Product : Recommendation : The product may be hazardous waste due to the potential lead content.

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Assure disposal of all waste generated by the spill complies with the Local, State and Federal regulations. **Packaging :** Recommendation : Disposal must be done according to official regulations.

14. TRANSPORT INFORMATION

International regul	ations	5			
Road & Rail Trans	port ((ADR/RID)	- Sea Transport (IMDG)	- Air	Transport (ICAO/IATA) :
Non-dangerous good	ls.				
Label	:	None	Number of statistics	:	8311 3000

15. REGULATORY INFORMATION

Information on the Xn : harmful	warning label				
R - phrases :	R21/22 : Harmful in contact with skin and if swallowed.				
S - phrases :	S20/21 : When using do not eat, drink or smoke.				
	S37 : Wear suitable gloves.				
Other Legal Regulations					
German water pollution risk (WGK) :		NWG (Tin) 2 (Lead) 3 (Silver)			
Substances that aff	ect the ozone layer :	Substances that affect the ozone layer are not present in this preparation and are not used for its production.			
EINECS	:	All ingredients have been registered.			

16. OTHER INFORMATION

Product information in other European languages can be obtained at *Interflux[®] Solder NV*, 9042 *Gent.* Because we cannot anticipate or control the many different conditions under which this information and our products may be used, we do not guarantee the applicability or the accuracy of this information or the suitability of our products in any given situation. Users of our products should make their own tests to determine the suitability of each such product for their particular purposes. The products discussed are sold without such warranty, either expressed or implied.

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